Test Beam Studies of Prototype Modules for the ATLAS ITk Strip Detector

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Overview of the ATLAS ITk Strip Detector

- Replacement of the ATLAS Inner Detector with the Inner Tracker (ITk) for the Phase-II upgrade
- The strip detector has a silicon area of ~165m² and ~18k modules





ATLAS ITk Strip Modules

- n⁺-in-p float zone silicon sensors, active area ~10x10cm², 300µm thickness and 74.5µm strip pitch
- > Hybrids glued directly to silicon sensors
- ATLAS Binary read-out Chip (ABC) and Hybrid Controller Chip (HCC) glued and wire-bonded to hybrid
- Module production expected to start in 2020







DUTs and Measurement Points

- Inner end-cap module (R0) with radial strips
- Short Strip barrel module (SS) with power board (FEAST chip)

EC R0

Barrel SS



Lengthy procedure for every DUT



Set-up

- > EUDET-type telescope + FE-I4 plane
- Cooling with Peltier elements + water:
 - we could not reach the target temperature
- > Among the first EUDAQ2 users
- Custom EUTelescope with GBL





Radial Reconstruction

> End-cap R0 module has radial strips with rotated annulus shape



Modifications to GBL code for radial geometry:

- 1) Pattern Recognition: to assign a DUT hit to a track a criterion on the angular distance track/hit is set
- 2) Track Fitting/Alignment: the residuals are calculated in radial coordinates



Residuals and Tracking Resolution

- Tracking resolution estimated fitting with smeared error function
- >≈6µm tracking resolution at DESY @ 4.8GeV





Efficiency

- > Efficiency comparable in all the positions for both DUTs
- Median Charge ≈4fC (25k electrons)
- > Fluctuations mainly due to calibration





Inter-strip Cluster Size and Efficiency





Effect of Hybrid/Glue

The effects of gluing the hybrid directly on the sensor are not totally know



- Small (0.02) increase of cluster size in strips with glue
- Effect on the future operations totally negligible



Long Term Effects

- Probe station measurements found some long term effects over time scales of days, in particular for underbiased sensors (V_{dep}≈300V)
- > Threshold scans performed with EC R0 at the beginning of beam time and after ≈5 days of bias at 400V



Collected charge is decreased by more than 10% at 200 and 300V

Charge sharing visibly increased



Bond Pads/Edge Efficiency

> Bond pads show a clear signature on the direction along the strip

bond pad: 200 µm p-stop area: 350 µm





Bond Pads/Edge Efficiency

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Very good reference to test the position of efficiency drop



Performance of the last iteration of prototype modules generally consistent with expectations

Some effects have to be further investigated

> Plans for 2018:

- new sensor iteration
- new FE chip
- double sided objects



Backup: Probe Station Long Term Effect





Backup: EC R0 Cluster Size





Edoardo Rossi | BTTB6 | 18th January 2018 | Page 16